



Product Change Notice: SEMC Series (eMMC) SD Cards Packaging Change

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<p>About This Notice:</p>	<p>eMMC packing specification will be changed as attached.</p> <ol style="list-style-type: none"> 1. Desiccant 2. Bubble wrap will be used as a spacer instead of empty trays
<p>Effective Date:</p>	<p>November 2018 (exact date is TBD)</p>
<p>Change Details:</p>	<p>1.Desiccant</p> <p>Current:</p>  <p>New:</p>  <p>2.Packing Current packing: 4 empty trays are packed as spacer. New packing: Instead of empty trays, bubble wrap will be used.</p>
<p>Affected Parts:</p>	<p>RP-SEMC08DA1, RP-SEMC16DA1, RP-SEMC32DA1</p>
<p>Datasheet(s):</p>	<p>As attached.</p>
<p>Notes:</p>	<p>*This change will not affect the performance of the product.</p>